

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P _D	300	mW
Power Derating Factor above +100°C	P _{DER}	2.4	mW/°C
Output Current	I _{OUT}	400	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C
Thermal Resistance, Junction to Ambient Air (Note 5)	R _{θJA}	417	°C/W

Maximum Ratings:
Pre-Biased PNP Transistor (Q1) (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-50	V
Collector-Emitter Voltage	V _{CEO}	-50	V
Supply Voltage	V _{CC}	-50	V
Input Voltage	V _{IN}	-6 to +5	V
Output Current	I _C	-400	mA

Maximum Ratings:
ESD Protected N-Channel MOSFET (Q2) (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	V _{DSS}	60	V
Drain Gate Voltage (R _{GS} ≤ 1MΩ)	V _{DGR}	60	V
Gate-Source Voltage	V _{GSS}	+/-20	V
		+/-40	
Drain Current (Note 5)	I _D	115	mA
		800	
Continuous Source Current	I _S	115	mA

Note: 5. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.

Electrical Characteristics: Pre-Biased PNP Transistor (Q1) (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)						
Collector-Base Cut Off Current	I _{CBO}	—	—	-500	nA	V _{CB} = -50V, I _E = 0
Collector-Emitter Cut Off Current	I _{CEO}	—	—	-1	μA	V _{CE} = -50V, I _B = 0
Collector-Base Breakdown Voltage	V _{(BR)CBO}	-50	—	—	V	I _C = -10μA, I _E = 0
Collector-Emitter Breakdown Voltage	V _{(BR)CEO}	-50	—	—	V	I _C = -2mA, I _B = 0
Input Off Voltage	V _{I(OFF)}	-0.3	—	—	V	V _{CE} = -5V, I _C = -100μA
Output Current	I _{O(OFF)}	—	—	-1	μA	V _{CC} = -50V, V _I = 0V
ON CHARACTERISTICS (Note 6)						
Collector-Emitter Saturation Voltage	V _{CE(SAT)}	—	-0.06	-0.15	V	I _C = -10mA, I _B = -0.3mA
		—	-0.18	-0.30	V	I _C = -300mA, I _B = -30mA
		—	-0.28	-0.60	V	I _C = -500mA, I _B = -50mA
DC Current Gain	h _{FE}	55	220	—	—	V _{CE} = -5V, I _C = -50mA
		55	260	—	—	V _{CE} = -5V, I _C = -100mA
		55	265	—	—	V _{CE} = -5V, I _C = -200 mA
		55	225	—	—	V _{CE} = -5V, I _C = -400mA
Input On Voltage	V _{I(ON)}	-3.0	-1.5	—	V _{DC}	V _O = -0.3V, I _I = -2mA
Input Current	I _i	—	-18	-45	mA	V _I = -5V
Base-Emitter Turn-on Voltage	V _{BE(ON)}	—	-1.2	-1.6	V	V _{CE} = -5V, I _C = -400mA
Base-Emitter Saturation Voltage	V _{BE(SAT)}	—	-1.9	-2.5	V	I _C = -50mA, I _B = -5mA
		—	-5.25	-6.00	V	I _C = -400mA, I _B = -20mA
Input Resistor (Base), +/- 30%	R2	0.154	0.220	0.286	KΩ	—
Pull-up Resistor (Base to V _{CC} supply), +/- 30%	R1	7	10	13	KΩ	—
Resistor Ratio (Input Resistor/Pullup resistor)	R1/R2	36	45	55	—	—
SMALL SIGNAL CHARACTERISTICS						
Gain Bandwidth Product	f _T	—	200	—	MHz	V _{CE} = -10V, I _E = -5mA, f = 100MHz

* Pulse Test: Pulse width, t_p < 300μs, Duty Cycle, d ≤ 0.02

Note: 6. Short duration pulse test used to minimize self-heating effect.

Electrical Characteristics:
ESD Protected N-Channel MOSFET (Q2) (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	60	—	—	V	V _{GS} = 0V, I _D = 10μA
Zero Gate Voltage Drain Current	I _{DSS}	—	—	1	μA	V _{GS} = 0V, V _{DS} = 60V
Gate-Body Leakage Current, Forward	I _{GSSF}	—	—	0.95	mA	V _{GS} = 20V, V _{DS} = 0V
Gate-Body Leakage Current, Reverse	I _{GSSR}	—	—	-0.95	mA	V _{GS} = -20V, V _{DS} = 0V
ON CHARACTERISTICS (Note 6)						
Gate Source Threshold Voltage	V _{GS(th)}	1	1.6	2.5	V	V _{DS} = V _{GS} , I _D = 0.25mA
Static Drain-Source On-State Voltage	V _{DS(on)}	—	0.09	1.5	V	V _{GS} = 5V, I _D = 50mA
		—	0.6	3.75		V _{GS} = 10V, I _D = 500mA
On-State Drain Current	I _{D(on)}	500	—	—	mA	V _{GS} = 10V, V _{DS} ≥ 2*V _{DS(ON)}
Static Drain-Source On Resistance	R _{DS(on)}	—	1.6	3	Ω	V _{GS} = 5V, I _D = 50mA
		—	1.2	2		V _{GS} = 10V, I _D = 500mA
Forward Transconductance	g _{FS}	80	260	—	mS	V _{DS} ≥ 2*V _{DS(ON)} , I _D = 200 mA
Gate Pull-Down Resistor, +/- 35%	R3	—	37	—	kΩ	—
DYNAMIC CHARACTERISTICS						
Input Capacitance	C _{iss}	—	—	50	pF	V _{DS} = -25V, V _{GS} = 0V, f = 1MHz
Output Capacitance	C _{oss}	—	—	25	pF	
Reverse Transfer Capacitance	C _{rss}	—	—	5	pF	
SWITCHING CHARACTERISTICS*						
Turn-On Delay Time	t _{d(on)}	—	—	20	ns	V _{DD} = 30V, V _{GS} = 10V,
Turn-Off Delay Time	t _{d(off)}	—	—	40	ns	I _D = 200mA, R _G = 25Ω, R _L = 150Ω
SOURCE-DRAIN (BODY) DIODE CHARACTERISTICS AND MAXIMUM RATINGS						
Drain-Source Diode Forward On-Voltage	V _{SD}	—	0.88	1.5	V	V _{GS} = 0V, I _S = 300 mA*
Maximum Continuous Drain-Source Diode Forward Current (Reverse Drain Current)	I _S	—	—	300	mA	—
aximum Pulsed Drain-Source Diode Forward Current	I _{SM}	—	—	800	mA	—

* Pulse Test: Pulse width, t_p < 300μs, Duty Cycle, d ≤ 0.02

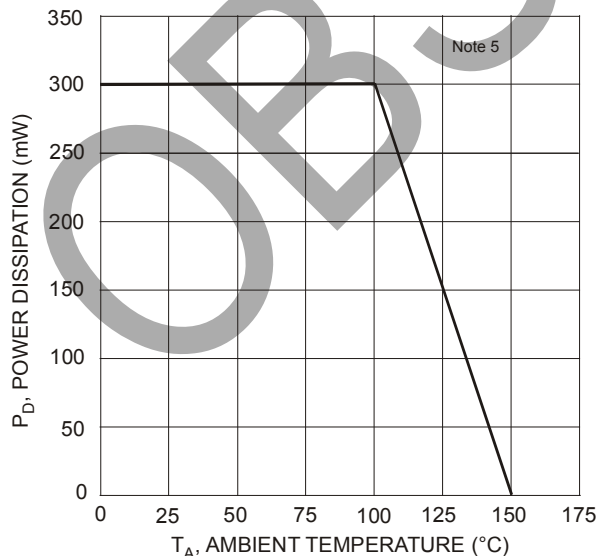


Fig. 3 Max Power Dissipation vs. Ambient Temperature

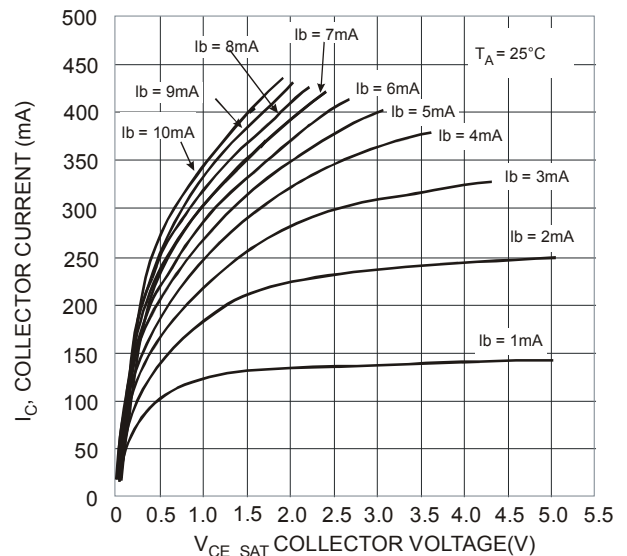


Fig. 4 Output Current vs. Voltage Drop (Pass Element PNP)

Pre-Biased PNP Transistor Characteristics

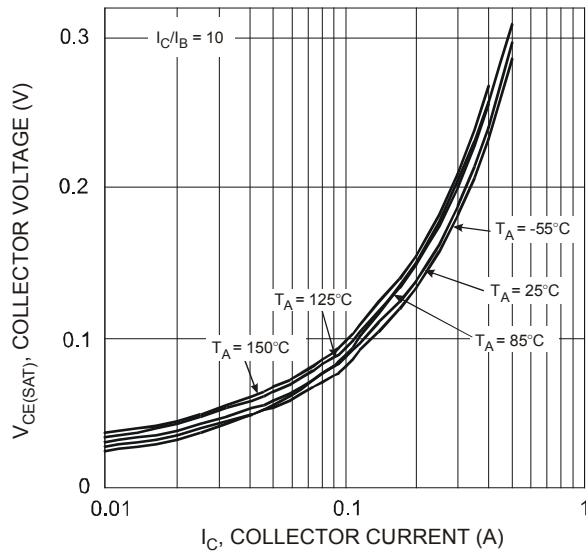


Fig. 5 $V_{CE(SAT)}$ vs. I_C

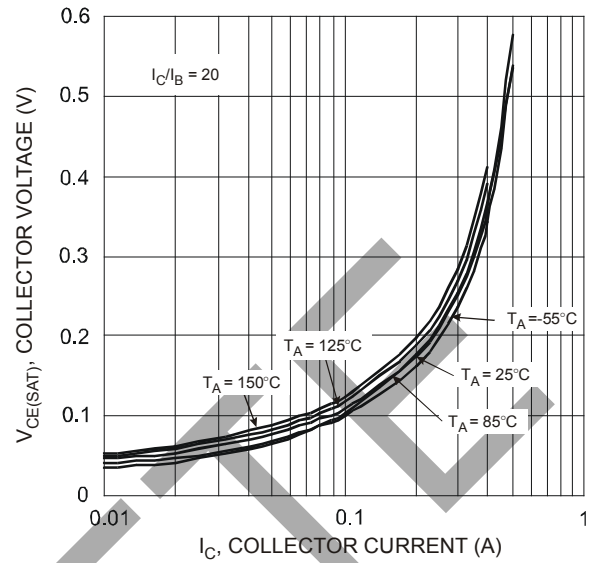


Fig. 6 $V_{CE(SAT)}$ vs. I_C

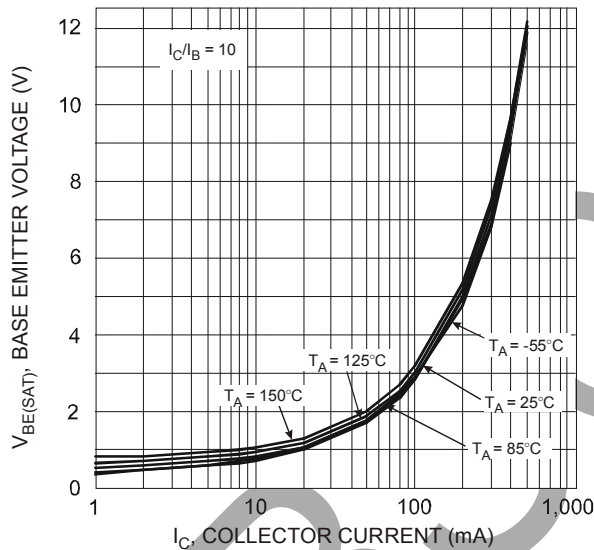


Fig. 7 $V_{BE(SAT)}$ vs. I_C

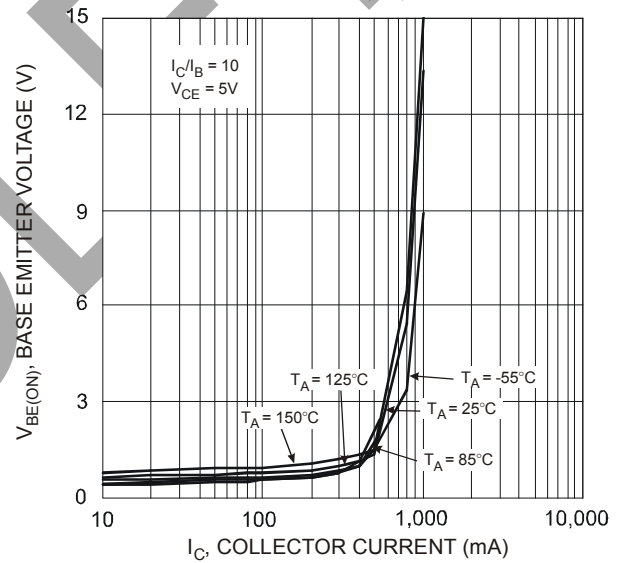


Fig. 8 $V_{BE(ON)}$ vs. I_C

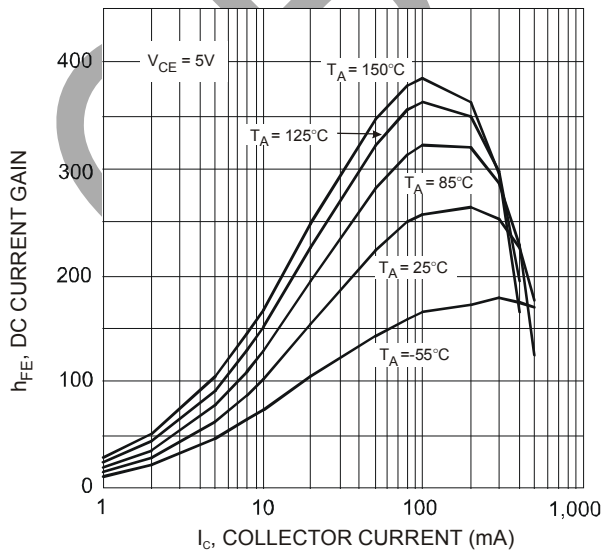
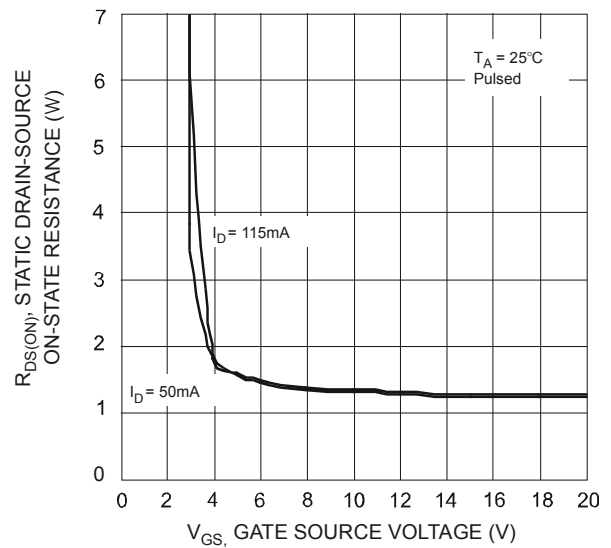
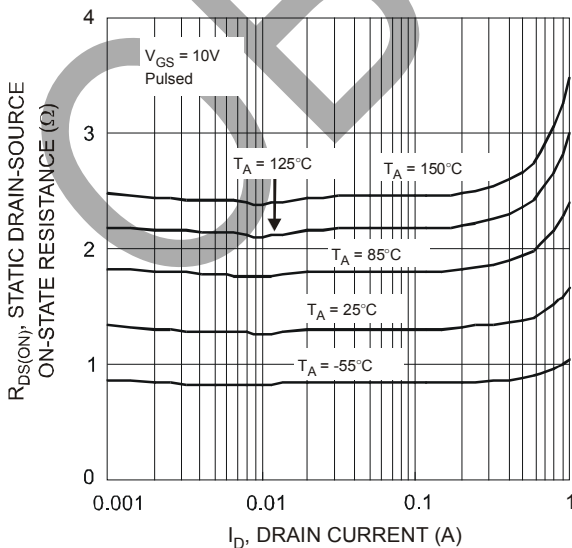
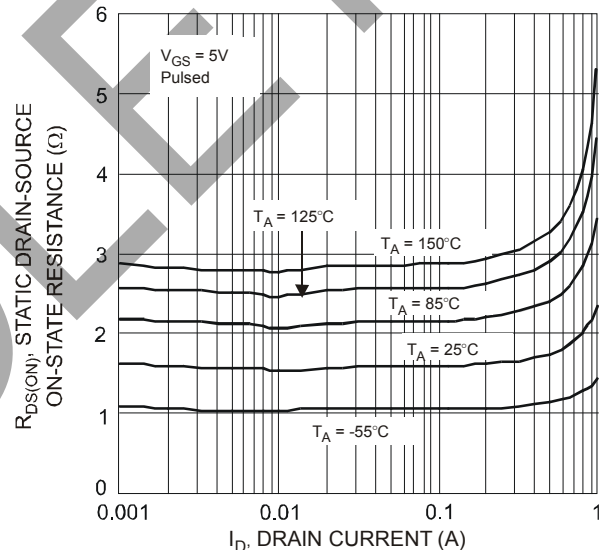
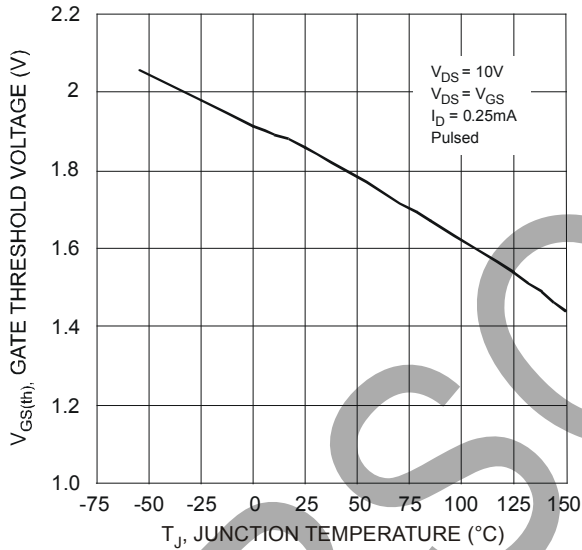
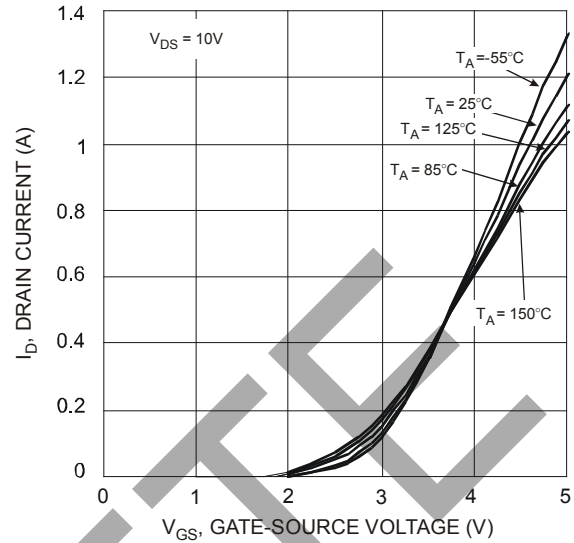
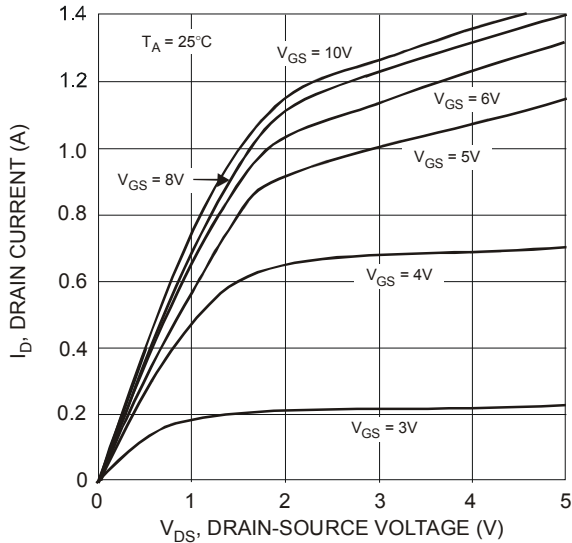


Fig. 9 h_{FE} vs. I_C

Typical N-Channel MOSFET (Q2) Characteristics



Typical N-Channel MOSFET (Q2) Characteristics (cont.)

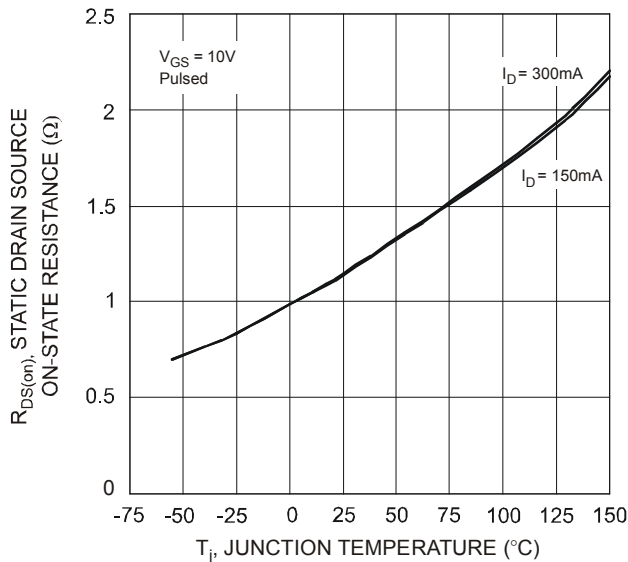


Fig. 16 Static Drain-Source On-State Resistance vs. Junction Temperature

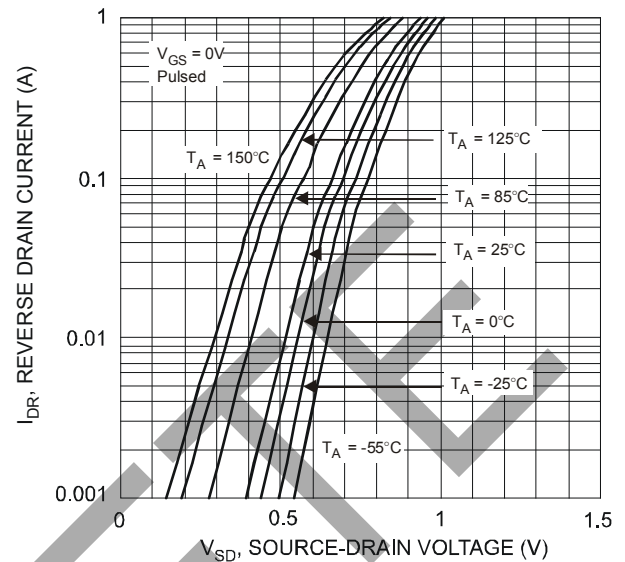


Fig. 17 Reverse Drain Current vs. Source-Drain Voltage

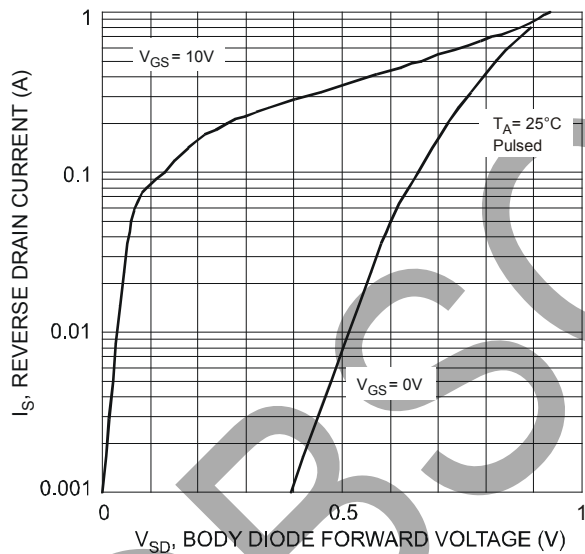


Fig. 18 Reverse Drain Current vs. Source-Drain Voltage

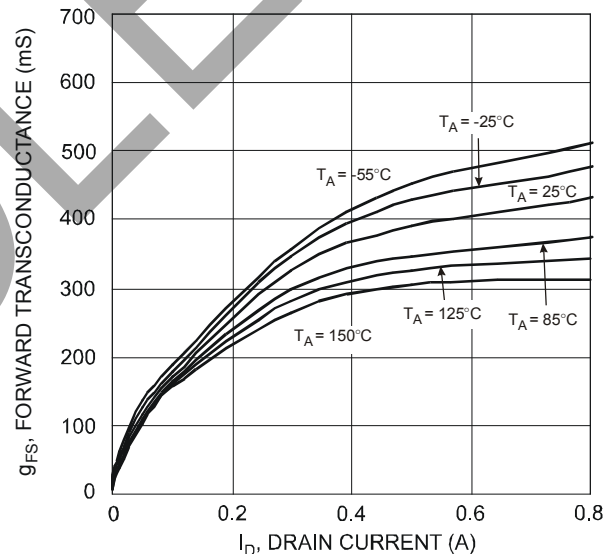


Fig. 19 Forward Transconductance vs. Drain Current ($V_{DS} > I_D \cdot R_{DS(on)}$)

OBSOLETE - PART DISCONTINUED

Application Details

PNP Transistor and ESD Protected N-MOSFET integrated as one in LMN400E01 can be used as a discrete entity for general applications or as an integrated circuit to function as a Load Switch. When it is used as the latter as shown in Figure 20, various input voltage sources can be used as long as it does not exceed the maximum ratings of the device. These devices are designed to deliver continuous output load current up to a maximum of 400mA. The MOSFET Switch draws no current, hence the loading of the control circuitry is prevented. Care must be taken for higher levels of dissipation while designing for higher load conditions. These devices provide high power and also consume less space. The product mainly helps in optimizing power usage, thereby conserving battery life in a controlled load system like portable battery powered applications. (Please see Figure 21 for one example of a typical application circuit used in conjunction with a voltage regulator as a part of power management system).

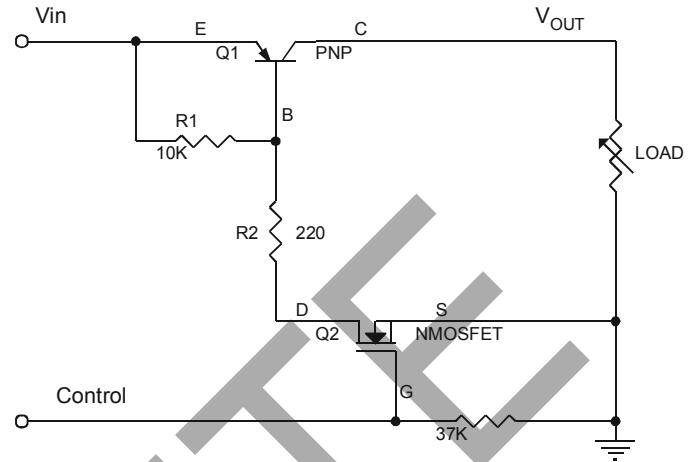


Figure 20 Circuit Diagram

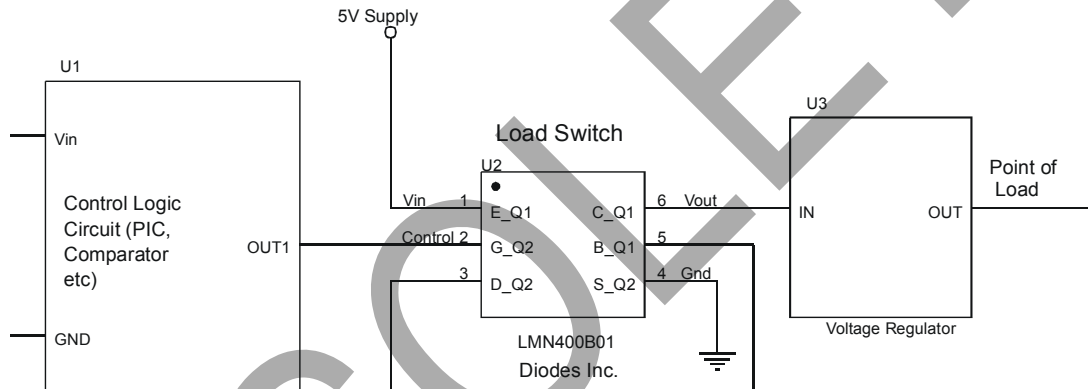
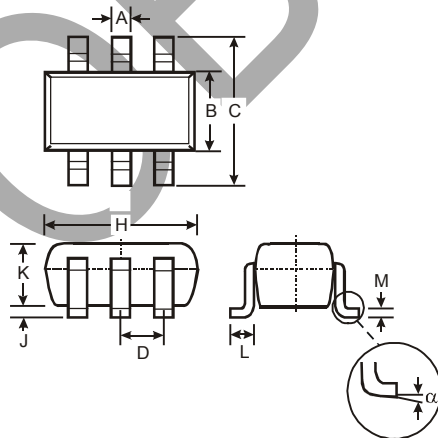


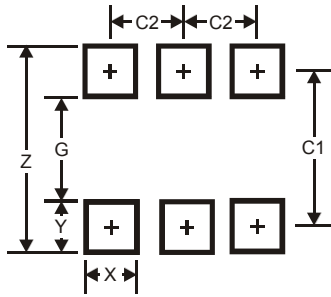
Figure 21 Typical Application Circuit

Package Outline Dimensions



SOT26			
Dim	Min	Max	Typ
A	0.35	0.50	0.38
B	1.50	1.70	1.60
C	2.70	3.00	2.80
D	—	—	0.95
H	2.90	3.10	3.00
J	0.013	0.10	0.05
K	1.00	1.30	1.10
L	0.35	0.55	0.40
M	0.10	0.20	0.15
α	0°	8°	—
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
Z	3.20
G	1.60
X	0.55
Y	0.80
C1	2.40
C2	0.95

OBSOLETE - PART DISCONTINUED

OBSOLETE

IMPORTANT NOTICE

1. DIODES INCORPORATED AND ITS SUBSIDIARIES ("DIODES") MAKE NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO ANY INFORMATION CONTAINED IN THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).
2. The Information contained herein is for informational purpose only and is provided only to illustrate the operation of Diodes products described herein and application examples. Diodes does not assume any liability arising out of the application or use of this document or any product described herein. This document is intended for skilled and technically trained engineering customers and users who design with Diodes products. Diodes products may be used to facilitate safety-related applications; however, in all instances customers and users are responsible for (a) selecting the appropriate Diodes products for their applications, (b) evaluating the suitability of the Diodes products for their intended applications, (c) ensuring their applications, which incorporate Diodes products, comply the applicable legal and regulatory requirements as well as safety and functional-safety related standards, and (d) ensuring they design with appropriate safeguards (including testing, validation, quality control techniques, redundancy, malfunction prevention, and appropriate treatment for aging degradation) to minimize the risks associated with their applications.
3. Diodes assumes no liability for any application-related information, support, assistance or feedback that may be provided by Diodes from time to time. Any customer or user of this document or products described herein will assume all risks and liabilities associated with such use, and will hold Diodes and all companies whose products are represented herein or on Diodes' websites, harmless against all damages and liabilities.
4. Products described herein may be covered by one or more United States, international or foreign patents and pending patent applications. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks and trademark applications. Diodes does not convey any license under any of its intellectual property rights or the rights of any third parties (including third parties whose products and services may be described in this document or on Diodes' website) under this document.
5. Diodes products are provided subject to Diodes' Standard Terms and Conditions of Sale (<https://www.diodes.com/about/company/terms-and-conditions/terms-and-conditions-of-sales/>) or other applicable terms. This document does not alter or expand the applicable warranties provided by Diodes. Diodes does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel.
6. Diodes products and technology may not be used for or incorporated into any products or systems whose manufacture, use or sale is prohibited under any applicable laws and regulations. Should customers or users use Diodes products in contravention of any applicable laws or regulations, or for any unintended or unauthorized application, customers and users will (a) be solely responsible for any damages, losses or penalties arising in connection therewith or as a result thereof, and (b) indemnify and hold Diodes and its representatives and agents harmless against any and all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim relating to any noncompliance with the applicable laws and regulations, as well as any unintended or unauthorized application.
7. While efforts have been made to ensure the information contained in this document is accurate, complete and current, it may contain technical inaccuracies, omissions and typographical errors. Diodes does not warrant that information contained in this document is error-free and Diodes is under no obligation to update or otherwise correct this information. Notwithstanding the foregoing, Diodes reserves the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes.
8. Any unauthorized copying, modification, distribution, transmission, display or other use of this document (or any portion hereof) is prohibited. Diodes assumes no responsibility for any losses incurred by the customers or users or any third parties arising from any such unauthorized use.

Copyright © 2021 Diodes Incorporated

www.diodes.com

OBSOLETE - PART DISCONTINUED